

APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	[FLIP-CHIP DIE AND FLIP-CHIP PACKAGE SUBSTRATE]
Application Type :	regular, utility
Attorney Docket Number :	8810-US-PA-1
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Customer Number:	31561
	
Continuing Data:	
This is a Division of US application number 10064062, filed 2002-06-06 , now pending.	
Priority Data:	
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